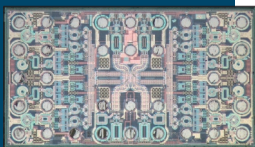
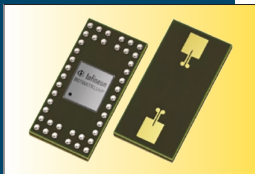


2025 Flip Chip and WLP: Trends and Market Forecasts



Demand for flip chip continues for a wide variety of products from consumer to AI data centers. Fan-in WLP demand continues to be driven by its use in smartphones and other consumer applications. The growing FO-WLP market is divided into four segments: high-density round carrier, low-density round carrier, low-density panel, and high-density panel. The main driver for panel level packaging is cost reduction, but companies are also looking for larger form factors to support the growing body size. Capacity expansion is documented and imbalances in supply and demand across the industry are analyzed.

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1.4 Hybrid Bonding

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